

Title (en)
POWER MODULE

Title (de)
LEISTUNGSMODUL

Title (fr)
MODULE DE PUISSANCE

Publication
EP 3488466 A1 20190529 (DE)

Application
EP 17740361 A 20170707

Priority
• DE 102016217007 A 20160907
• EP 2017067094 W 20170707

Abstract (en)
[origin: WO2018046165A1] The invention relates to a power module comprising a semiconductor component (1) that is to be contacted on the top side and the underside. The invention is characterized in that the semiconductor component (1) is to be electrically contacted on the top side by a leadframe matrix (7) by means of contact pressure.

IPC 8 full level
H01L 23/495 (2006.01); **H01L 23/498** (2006.01)

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H01L 23/4951 (2013.01 - EP US); **H01L 23/49544** (2013.01 - EP US); **H01L 23/49551** (2013.01 - EP US); **H01L 23/49838** (2013.01 - US); **H01L 23/49861** (2013.01 - EP US); **H01L 24/72** (2013.01 - EP US); **H01L 23/49579** (2013.01 - EP US); **H01L 25/072** (2013.01 - EP US)

Citation (search report)
See references of WO 2018046165A1

Designated contracting state (EPC)
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DE 102016217007 A1 20180308; CN 109661724 A 20190419; EP 3488466 A1 20190529; JP 2019531600 A 20191031; JP 6811310 B2 20210113; US 2019214340 A1 20190711; WO 2018046165 A1 20180315

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DE 102016217007 A 20160907; CN 201780054327 A 20170707; EP 17740361 A 20170707; EP 2017067094 W 20170707; JP 2019513030 A 20170707; US 201716330845 A 20170707